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## MA3X199 (MA199)

## Silicon epitaxial planar type

## For high voltage switching circuit

## Features

- High breakdown voltage: $\mathrm{V}_{\mathrm{R}}=200 \mathrm{~V}$
- Short reverse recovery time $\mathrm{t}_{\mathrm{rr}}$
- Automatic mounting is possible
- Absolute Maximum Ratings $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C}$

| Parameter | Symbol | Rating | Unit |
| :--- | :---: | :---: | :---: |
| Reverse voltage | $\mathrm{V}_{\mathrm{R}}$ | 200 | V |
| Repetitive peak reverse voltage | $\mathrm{V}_{\mathrm{RRM}}$ | 250 | V |
| Forward current (Average) | $\mathrm{I}_{\mathrm{F}(\mathrm{AV})}$ | 100 | mA |
| Repetitive peak forward current | $\mathrm{I}_{\mathrm{FRM}}$ | 225 | mA |
| Non-repetitive peak forward <br> surge current | $\mathrm{I}_{\mathrm{FSM}}$ | 500 | mA |
| Junction temperature | $\mathrm{T}_{\mathrm{j}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | $\mathrm{T}_{\text {stg }}$ | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |

Note) *: $\mathrm{t}=1 \mathrm{~s}$


Marking Symbol: M3A
Internal Connection


Electrical Characteristics $\mathrm{T}_{\mathrm{a}}=25^{\circ} \mathrm{C} \pm 3^{\circ} \mathrm{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
| :--- | :---: | :--- | :---: | :---: | :---: | :---: |
| Forward voltage | $\mathrm{V}_{\mathrm{F}}$ | $\mathrm{I}_{\mathrm{F}}=100 \mathrm{~mA}$ |  |  | 1.2 | V |
| Reverse current | $\mathrm{I}_{\mathrm{R}}$ | $\mathrm{V}_{\mathrm{R}}=200 \mathrm{~V}$ |  |  | 1.0 | $\mu \mathrm{~A}$ |
| Terminal capacitance | $\mathrm{C}_{\mathrm{t}}$ | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ |  | 3.0 | pF |  |
| Reverse recovery time * | $\mathrm{t}_{\mathrm{rr}}$ | $\mathrm{I}_{\mathrm{F}}=\mathrm{I}_{\mathrm{R}}=10 \mathrm{~mA}$ |  |  |  |  |
| $\mathrm{I}_{\mathrm{rr}}=1 \mathrm{~mA}, \mathrm{R}_{\mathrm{L}}=100 \Omega$ |  |  |  |  |  |  |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 20 MHz .
3. $*: \mathrm{t}_{\mathrm{rr}}$ measurement circuit


Note) The part number in the parenthesis shows conventional part number.






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